

Title (en)

Adhesive composition and insulating substrate clad with this composition used for producing printed-circuit boards.

Title (de)

Klebende Zusammensetzung und mit dieser Zusammensetzung bekleideter isolierender Träger unter Verwendung von gedruckten Schaltungsplatten.

Title (fr)

Composition adhésive et substrat isolant revêtu de cette composition utilisé pour la fabrication de plaquettes de circuits imprimés.

Publication

**EP 0192365 A2 19860827 (EN)**

Application

**EP 86300640 A 19860130**

Priority

JP 1962485 A 19850204

Abstract (en)

An insulating substrate having on at least one surface a layer of an adhesive composition comprising (A) a modified phenolic resin and (B) acrylonitrile-butadiene rubber is suitable for producing, by an additive process, printed circuit boards having excellent solder heat resistance.

IPC 1-7

**C08L 61/06**; **C08L 61/34**; **C09J 3/16**; **C23C 18/20**; **H05K 3/38**

IPC 8 full level

**C08G 8/24** (2006.01); **C08L 7/00** (2006.01); **C08L 9/02** (2006.01); **C08L 21/00** (2006.01); **C08L 33/00** (2006.01); **C08L 33/02** (2006.01); **C08L 61/00** (2006.01); **C08L 61/04** (2006.01); **C08L 61/06** (2006.01); **C08L 61/10** (2006.01); **C09J 109/02** (2006.01); **C09J 121/00** (2006.01); **C09J 161/00** (2006.01); **C09J 161/06** (2006.01); **C09J 161/34** (2006.01); **H05K 3/38** (2006.01); **H05K 3/18** (2006.01)

CPC (source: EP KR US)

**C08G 8/24** (2013.01 - EP US); **C09J 109/02** (2013.01 - EP KR US); **C09J 161/06** (2013.01 - EP US); **C09J 161/34** (2013.01 - EP US); **H05K 3/387** (2013.01 - EP US); **C08L 9/02** (2013.01 - EP US); **C08L 2666/08** (2013.01 - EP US); **C08L 2666/16** (2013.01 - EP US); **H05K 3/181** (2013.01 - EP US); **H05K 2201/0133** (2013.01 - EP US); **Y10S 428/901** (2013.01 - EP US); **Y10T 29/49124** (2015.01 - EP US); **Y10T 428/259** (2015.01 - EP US); **Y10T 428/31511** (2015.04 - EP US); **Y10T 428/31688** (2015.04 - EP US); **Y10T 428/31877** (2015.04 - EP US); **Y10T 428/31935** (2015.04 - EP US); **Y10T 428/31942** (2015.04 - EP US)

Cited by

EP0747399A3; EP0372477A1; KR101243355B1

Designated contracting state (EPC)

CH DE GB LI

DOCDB simple family (publication)

**EP 0192365 A2 19860827**; **EP 0192365 A3 19870722**; **EP 0192365 B1 19920415**; DE 3684799 D1 19920521; JP H0710967 B2 19950208; JP S61179282 A 19860811; KR 860006913 A 19860915; KR 900006138 B1 19900824; US 4837086 A 19890606

DOCDB simple family (application)

**EP 86300640 A 19860130**; DE 3684799 T 19860130; JP 1962485 A 19850204; KR 860000717 A 19860203; US 82472686 A 19860131